

GTVA212701FA

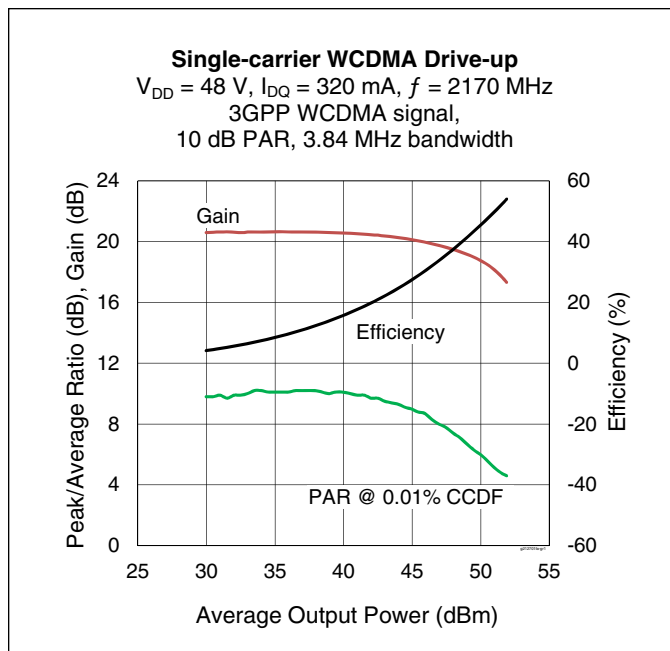
Thermally-Enhanced High Power RF GaN on SiC
Amplifier, 270 W, 48 V, 2110 – 2200 MHz

Description

The GTVA212701FA is a 270-watt GaN on SiC HEMT D-mode amplifier for use in the 2110 to 2200 MHz frequency band. It features input matching, high efficiency, and a thermally-enhanced earless package.



Package Types: H-87265J-2



Features

- GaN on SiC HEMT technology
- Input matched
- Typical pulsed CW performance (class AB), 2180 MHz, 48 V, 10 μs pulse width, 10% duty cycle
 - Output power $P_{3dB} = 300\text{ W}$
 - Drain efficiency = 68.5%
 - Gain = 17.5 dB
- Human Body Model Class 1B (per ANSI/ESDA/JEDEC JS-001)
- Capable of handling 10:1 VSWR @ 48 V, 56.2 W (WCDMA) output power
- Low thermal resistance
- Pb-free and RoHS-compliant

RF Characteristics

Single-carrier WCDMA Specifications (tested in the test fixture)

$V_{DD} = 48\text{ V}$, $I_{DQ} = 320\text{ mA}$, 56.2 W average output power, $f = 2180\text{ MHz}$. 3GPP WCDMA signal: 3.84 MHz channel bandwidth, 10 dB PAR at 0.01% CCDF.

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Gain	G_{ps}	18	19	—	dB
Drain Efficiency	η_D	35	38	—	%
Adjacent Channel Power Ratio	ACPR	—	-29	-26	dBc
Output PAR @ 0.01% CCDF	OPAR	6.4	7.0	—	dB

Note:

All published data at $T_{CASE} = 25^\circ\text{C}$ unless otherwise indicated

ESD: Electrostatic discharge sensitive device—observe handling precautions!



DC Characteristics

Characteristic	Symbol	Min.	Typ.	Max.	Unit	Conditions
Drain-source Breakdown Voltage	$V_{BR(DSS)}$	150	—	—	V	$V_{GS} = -8\text{ V}, I_D = 10\text{ mA}$
Drain-source Leakage Current	I_{DSS}	—	—	4.5	mA	$V_{GS} = -8\text{ V}, V_{DS} = 10\text{ V}$
Gate Threshold Voltage	$V_{DSX(th)}$	-3.8	-3.0	-2.3	V	$V_{DS} = 10\text{ V}, I_D = 32\text{ mA}$

Recommended Operating Conditions

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Drain Operating Voltage	V_{DD}	0	—	50	V	
Gate Quiescent Voltage	$V_{GS(Q)}$	-3.4	-3.0	-2.5		$V_{DS} = 48\text{ V}, I_D = 320\text{ mA}$

Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source Voltage	V_{DSS}	125	V
Operating Voltage	V_{DD}	55	
Gate-Source Voltage	V_{GS}	-10 to +2	
Gate Current	I_G	32	mA
Drain Current	I_D	12	A
Junction Temperature	T_J	225	°C
Storage Temperature Range	T_{STG}	-65 to +150	

Operation above the maximum values listed here may cause permanent damage. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the component. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. For reliable continuous operation, the device should be operated within the operating voltage range (V_{DD}) specified above.

Thermal Characteristics ($T_{CASE} = 70^\circ\text{C}$, 56.2 W (CW), 48 V, $I_{DQ} = 320\text{ mA}$, 2170 MHz)

Characteristic	Symbol	Value	Unit
Thermal Resistance	$R_{\theta JC}$	1.1	°C/W

Ordering Information

Type and Version	Order Code	Package	Shipping
GTVA212701FA V2 R0	GTVA212701FA-V2-R0	H-87265J-2, single-ended, earless flange	Tape & Reel, 50 pcs
GTVA212701FA V2 R2	GTVA212701FA-V2-R2	H-87265J-2, single-ended, earless flange	Tape & Reel, 250 pcs

Typical Performance (data taken in the production test fixture)

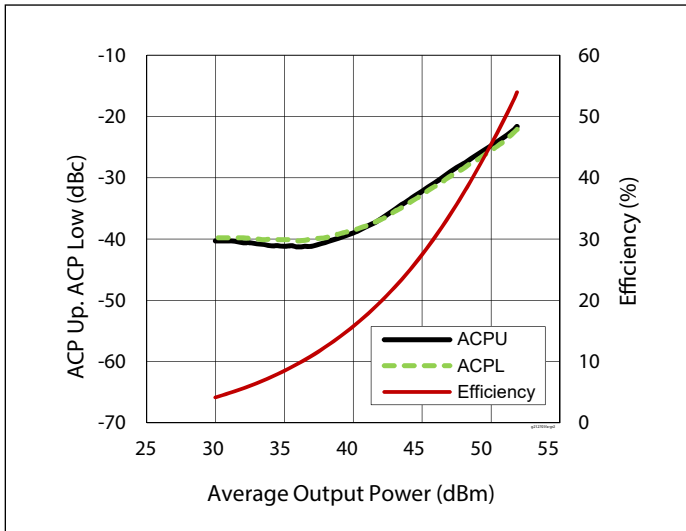


Figure 1. Single-carrier WCDMA Drive-up

$V_{DD} = 48\text{ V}$, $I_{DQ} = 320\text{ mA}$, $f = 2170\text{ MHz}$
 3GPP WCDMA signal, 10 dB PAR,
 3.84 MHz bandwidth

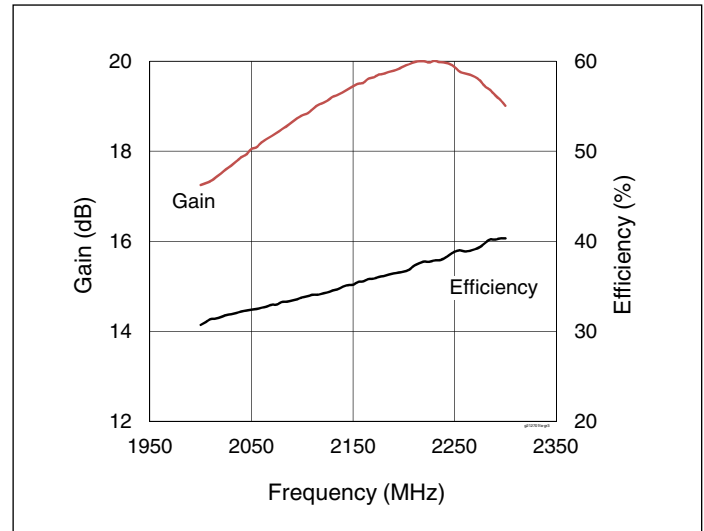


Figure 2. Single-carrier WCDMA Broadband

$V_{DD} = 48\text{ V}$, $I_{DQ} = 320\text{ mA}$,
 $P_{OUT} = 47.5\text{ dBm}$
 3GPP WCDMA signal, 10 dB PAR

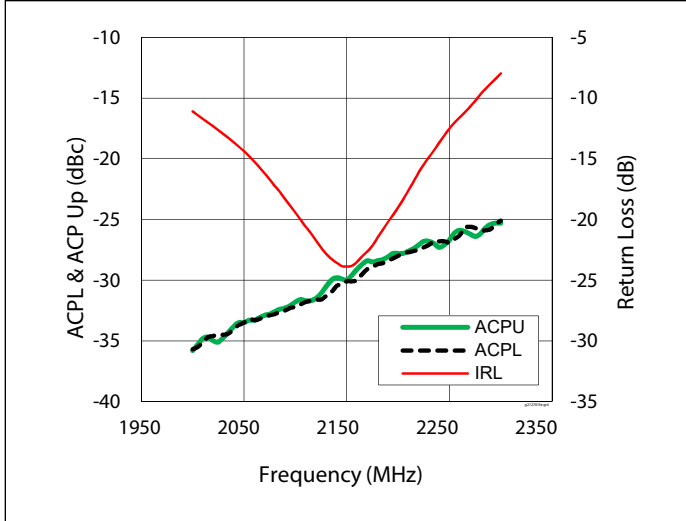


Figure 3. Single-carrier WCDMA Broadband

$V_{DD} = 48\text{ V}$, $I_{DQ} = 320\text{ mA}$,
 $P_{OUT} = 47.5\text{ dBm}$
 3GPP WCDMA signal, 10 dB PAR

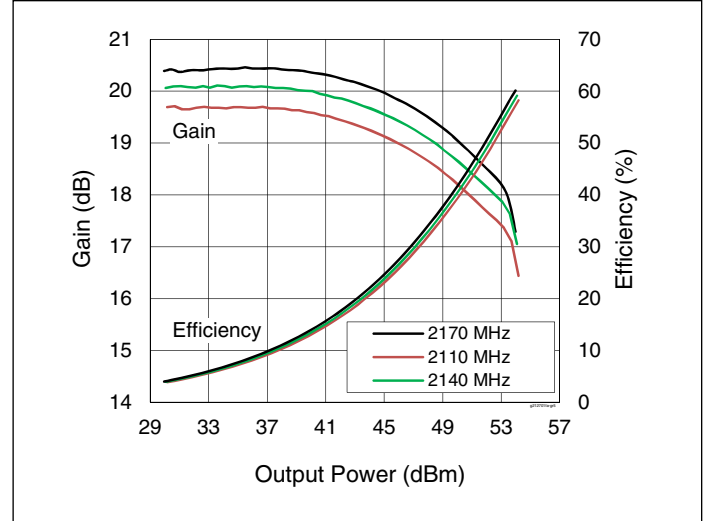


Figure 4. CW Performance Across Frequency

$V_{DD} = 48\text{ V}$, $I_{DQ} = 320\text{ mA}$

Typical Performance (cont.)

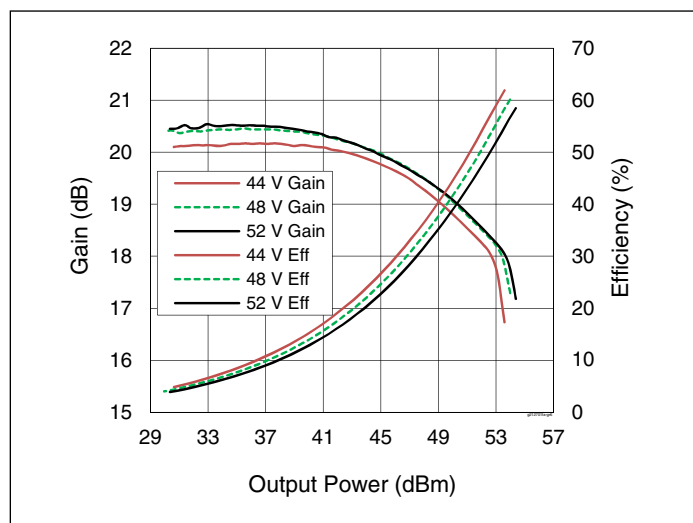


Figure 5. CW Performance at Various V_{DD}

$I_{DQ} = 320$ mA, $f = 2170$ MHz

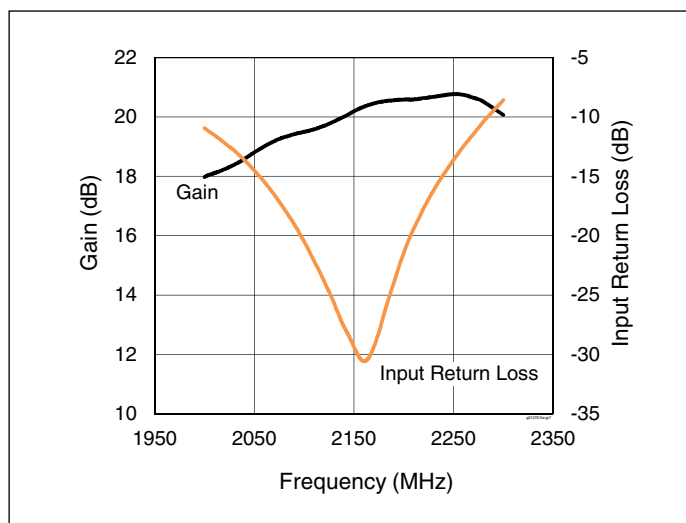


Figure 6. CW Small Signal Performance

$V_{DD} = 48$ V, $I_{DQ} = 320$ mA

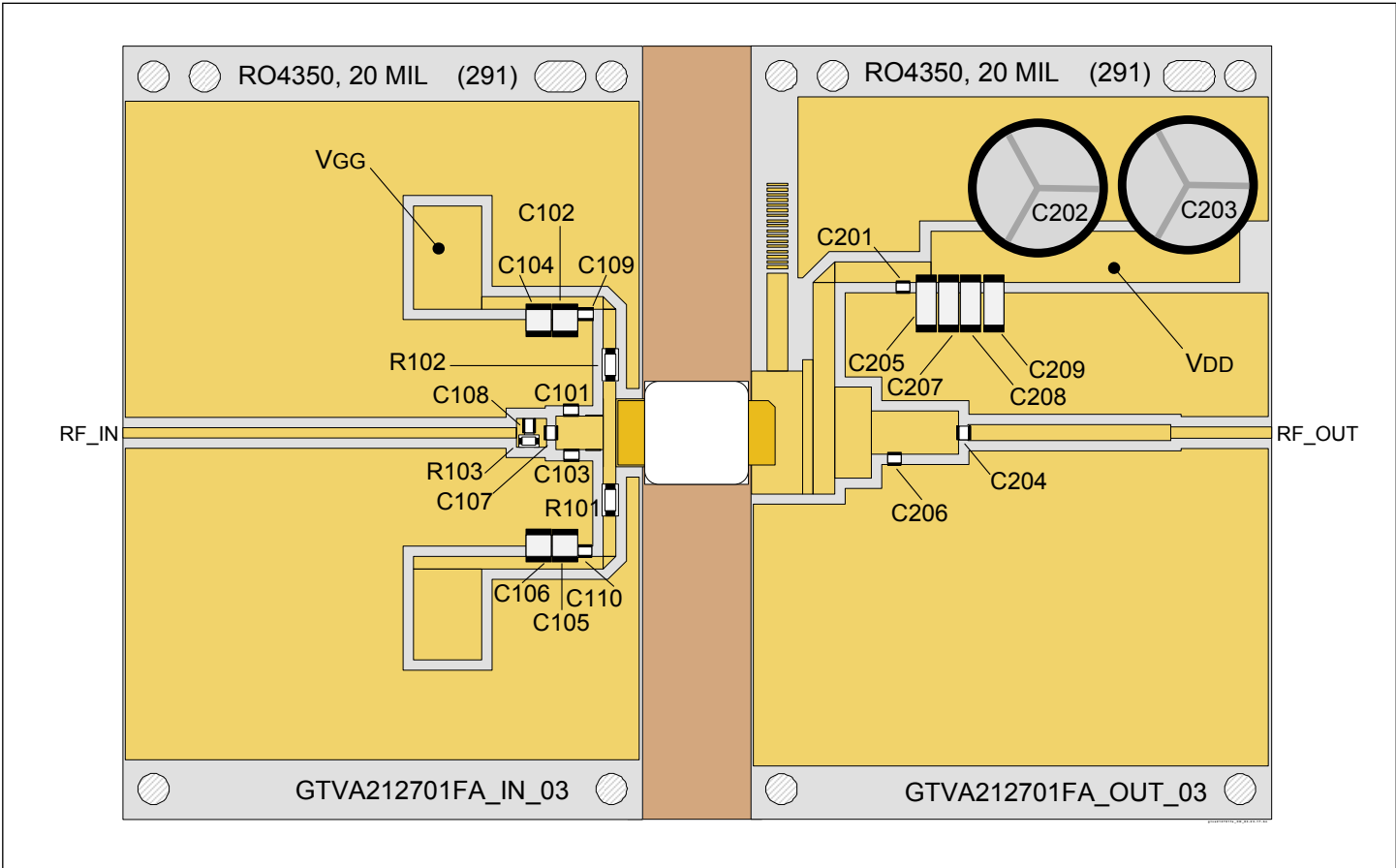
Load Pull

Pulsed CW signal: – 10 μ sec, 10% duty cycle; $V_{DD} = 48$ V, $I_{DQ} = 300$ mA

Class AB		P_{3dB}									
		Max Output Power					Max Drain Efficiency				
		Zl [Ω]	Gain [dB]	P_{3dB} [dBm]	P_{3dB} [W]	η_D [%]	Zl [Ω]	Gain [dB]	P_{3dB} [dBm]	P_{3dB} [W]	η_D [%]
Freq [MHz]	Zs [Ω]										
2110	6.38 – j6.61	3.01 – j3.1	17.28	55.72	373.2	67.5	3.01 – j1.41	18.57	54.74	297.6	73.9
2170	4.78 – j4.24	3.01 – j3.1	17.37	55.71	372.3	68.8	3.13 – j1.84	18.55	54.78	300.7	73.2
2200	4.09 – j4.3	3.01 – j3.1	16.97	55.80	380.2	65.6	3.08 – j1.97	18.6	54.88	307.6	74.7

Evaluation Board, 2110 to 2200 MHz

Evaluation Board Part Number	LTN/GTVA212701FA-V2
PCB Information	Rogers 4350, 0.508 mm [.020"] thick, 2 oz. copper, $\epsilon_r = 3.66$



Reference circuit assembly diagram (not to scale)

Components Information

Component	Description	Manufacturer	P/N
In			
C101	Capacitor, 2 pF	ATC	ATC800A2R0BT250XT
C102, C104, C105, C106	Capacitor, 10 μ F	Taiyo Yuden	UMK325C7106MM-T
C103	Capacitor, 0.2 pF	ATC	ATC800A0R2BT250XT
C107	Capacitor, 15 pF	ATC	ATC800A150GT250XT
C108	Capacitor, 12 pF	ATC	ATC800A120JT250XT
C109, C110	Capacitor, 24 pF	ATC	ATC800A240JT250XT
R101, R102	Resistor, 10 ohms	Panasonic Electronic Components	ERJ-8GEYJ100V
R103	Resistor, 10 ohms	Yageo	RC0805JR-0710RL
Out			
C201	Capacitor, 1.5 pF	ATC	ATC600S1R5CT250XT
C202, C210	Capacitor, 0.5 pF	ATC	ATC600S0R5CT250XT
C203	Capacitor, 1.0 pF	ATC	ATC600S1R0CT250XT
C204	Capacitor, 6.8 pF	ATC	ATC800A6R8CT250XT

Bias Sequencing

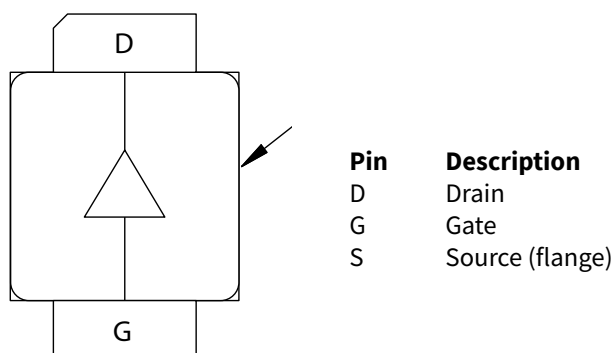
Bias On

1. Ensure RF is turned off
2. Apply pinch-off voltage of -5 V to the gate
3. Apply nominal drain voltage
4. Bias gate to desired quiescent drain current
5. Apply RF

Bias Off

1. Turn RF off
2. Apply pinch-off voltage to the gate
3. Turn-off drain voltage
4. Turn-off gate voltage

Pinout Diagram (top view)



Package Outline Specifications – Package H-87265J-2

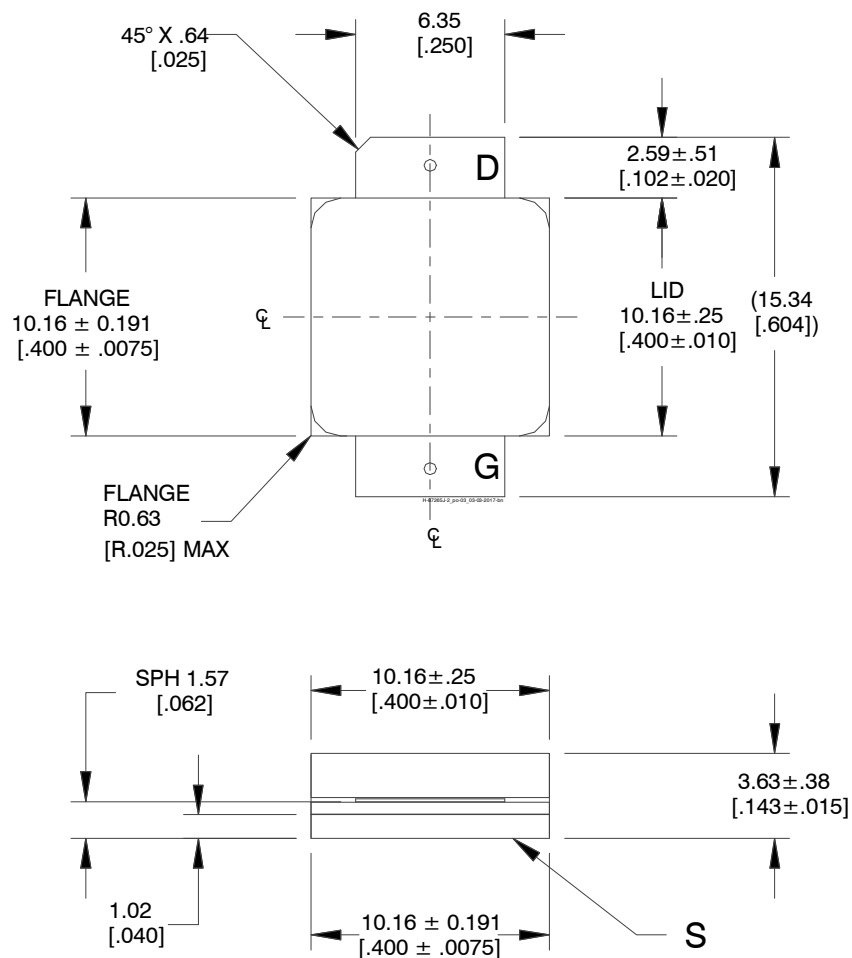


Diagram Notes—unless otherwise specified:

1. Interpret dimensions and tolerances per ASME Y14.5M-1994
2. Primary dimensions are mm; alternate dimensions are inches
3. All tolerances ± 0.127 [.005]
4. Pins: D – drain; G – gate; S – source
5. Lead thickness: 0.13 ± 0.05 mm [.005 ± .002 inch]
6. Gold plating thickness: 1.14 ± 0.38 micron [45 ± 15 microinch]

Notes & Disclaimer

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